



DE3831787

Biblio

Desc

Claims

Drawing

esp@cenet

Adhesion bonding method

Patent Number: DE3831787
Publication date: 1989-04-06
Inventor(s): PASCAL ROGER (FR)
Applicant(s): PASCAL ROGER (FR)
Requested Patent: ☐ DE3831787
Application Number: DE19883831787 19880919
Priority Number(s): FR19870013399 19870923
IPC Classification: C09J5/06; C09J7/00
EC Classification: B29C65/34, C09J5/06
Equivalents: ☐ ES2008030, ☐ FR2620648, ☐ JP1163283

Abstract

Method of bonding two elements, in which the adhesion element used is an adhesive heated by a heating element which in turn is formed by a conductive resistance element incorporated into the adhesion element. The conductive element may be a metal wire, for example of copper, steel or constantan, and may have the form of a lattice or of essentially parallel wires or fibres. The conducting element is supplied with electrical current.

Data supplied from the esp@cenet database - I2

3831787

FIG 1

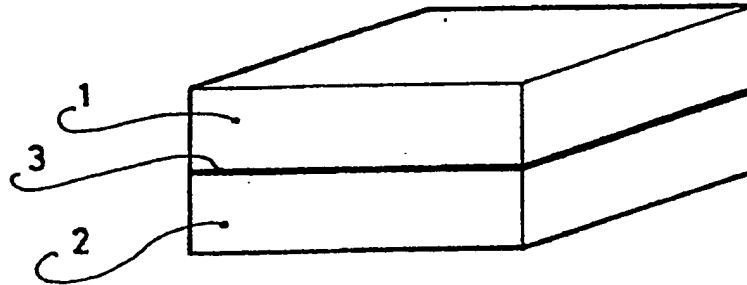


FIG 2

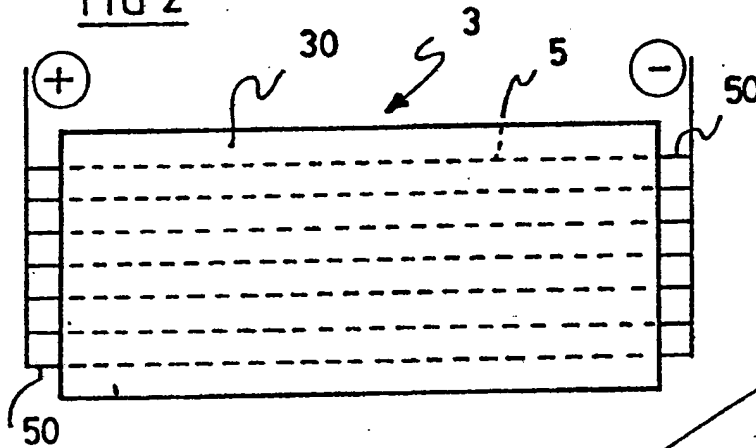


FIG 3



FIG 3a

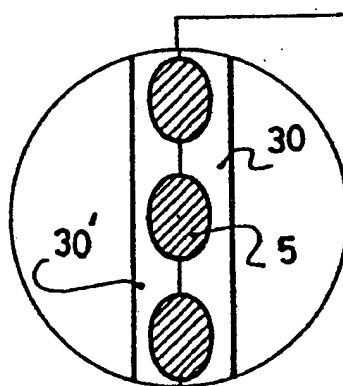


FIG 3'a

